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Fukumoto et al.

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(54) **SEMICONDUCTOR DEVICE**

6,300,685 B1 * 10/2001 Hasegawa et al. 257/780

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(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

Feb. 15, 2001 (JP) 2001-003331

(51) **LOC (7) Cl.** **13-03**

(52) **U.S. Cl.** **D13/182**

(58) **Field of Search** D13/182, 110; 174/52.2, 52.4, 16.3; 257/787, 668, 667, 670, 676, 679, 686, 688, 690-692, 696, 703, 778; 361/760, 783, 813, 752, 798, 820; 365/226

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(57) **CLAIM**

The ornamental design for a semiconductor device, as shown and described.

DESCRIPTION

FIG. 1 is a front, top and right side perspective view of a semiconductor device, showing our new design;

FIG. 2 is a front, bottom and right side perspective view thereof;

FIG. 3 is a front elevational view thereof;

FIG. 4 is a rear elevational view thereof;

FIG. 5 is a right side elevational view thereof; the left side elevational view is omitted as that is symmetrical to the right side elevational view thereof;

FIG. 6 is a top plan view thereof;

FIG. 7 is a bottom plan view thereof; and,

FIG. 8 is a cross-sectional view thereof, taken along line 8-8 of FIG. 5, with the internal system omitted.

1 Claim, 4 Drawing Sheets

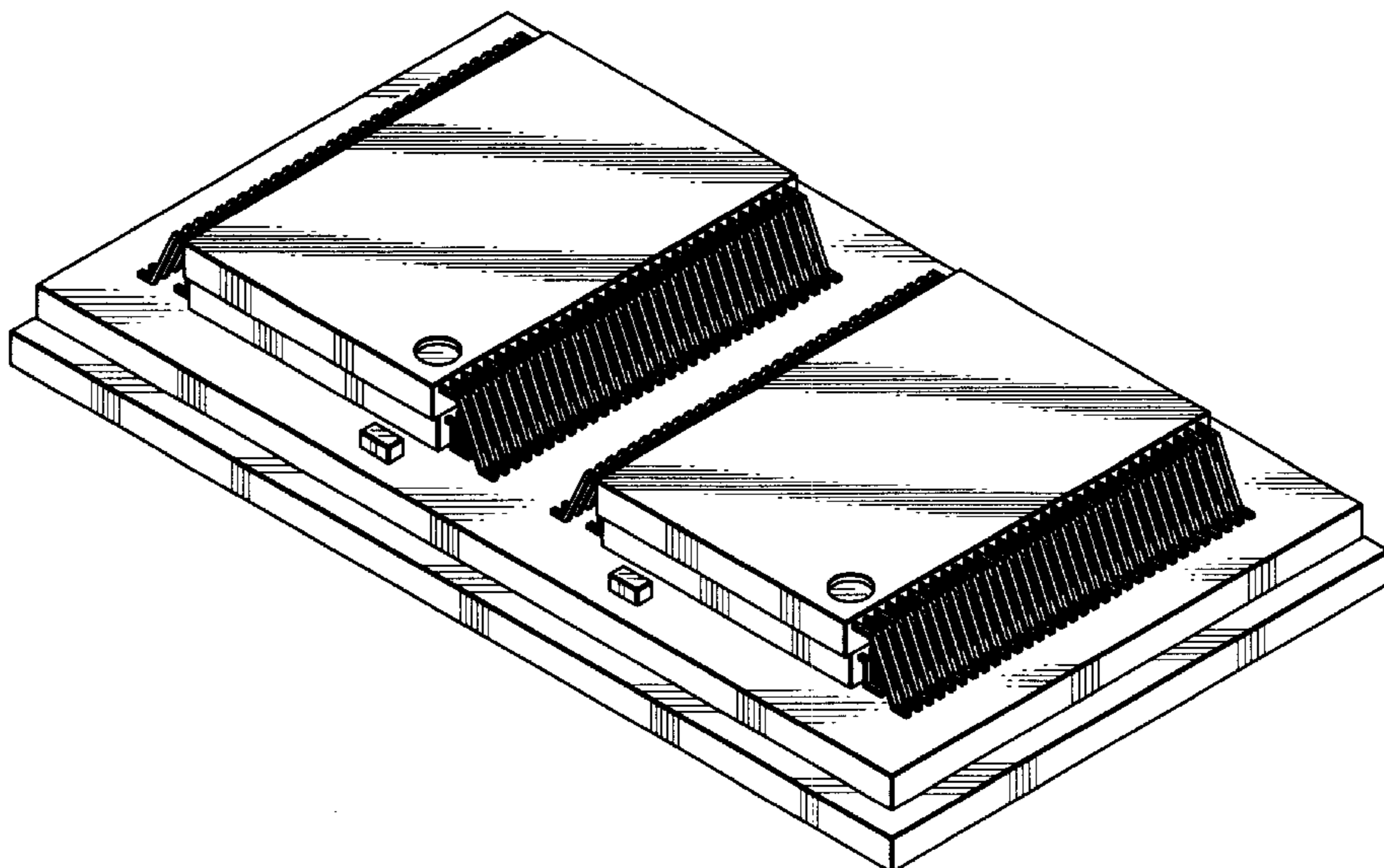


FIG. 1

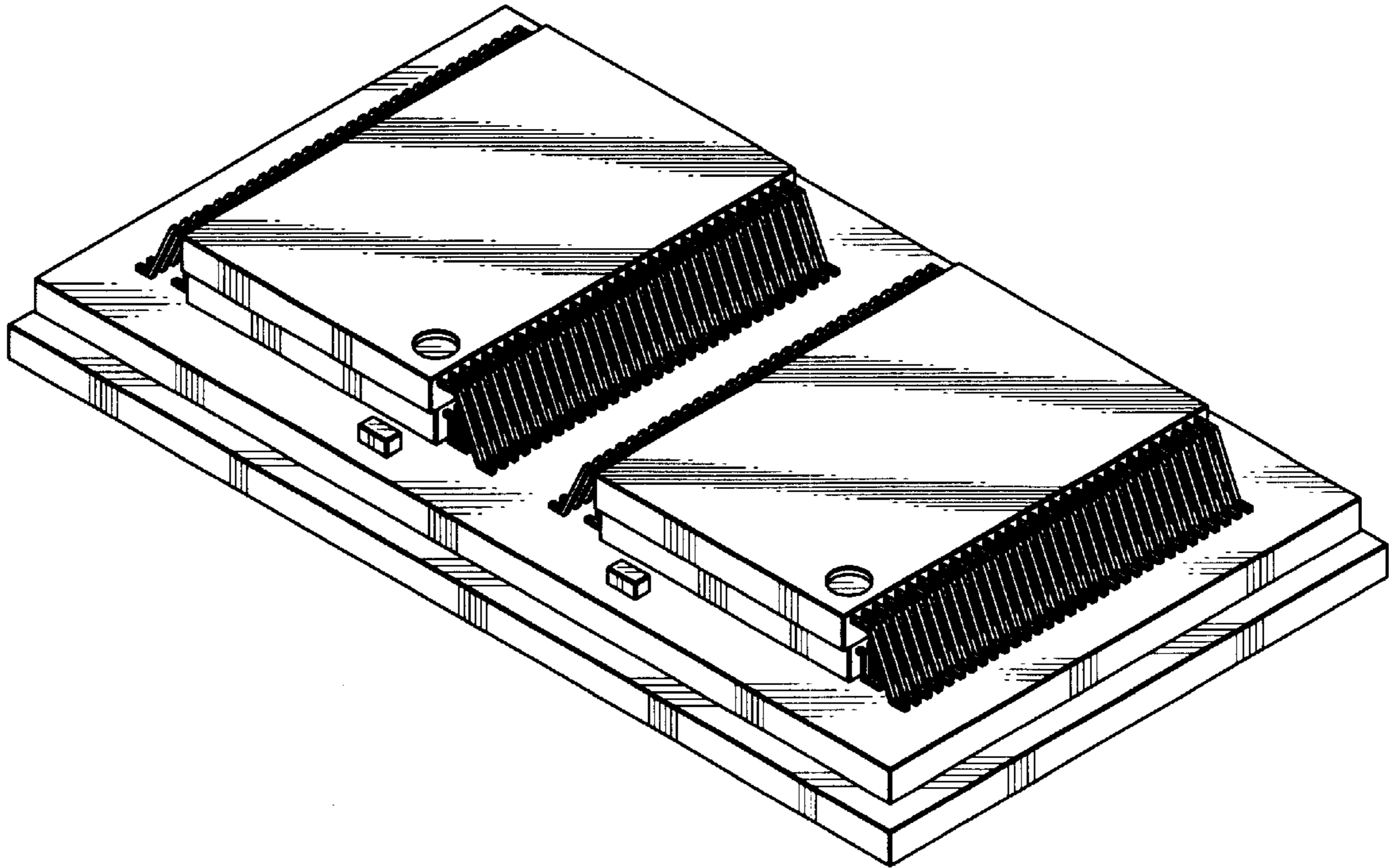


FIG. 2

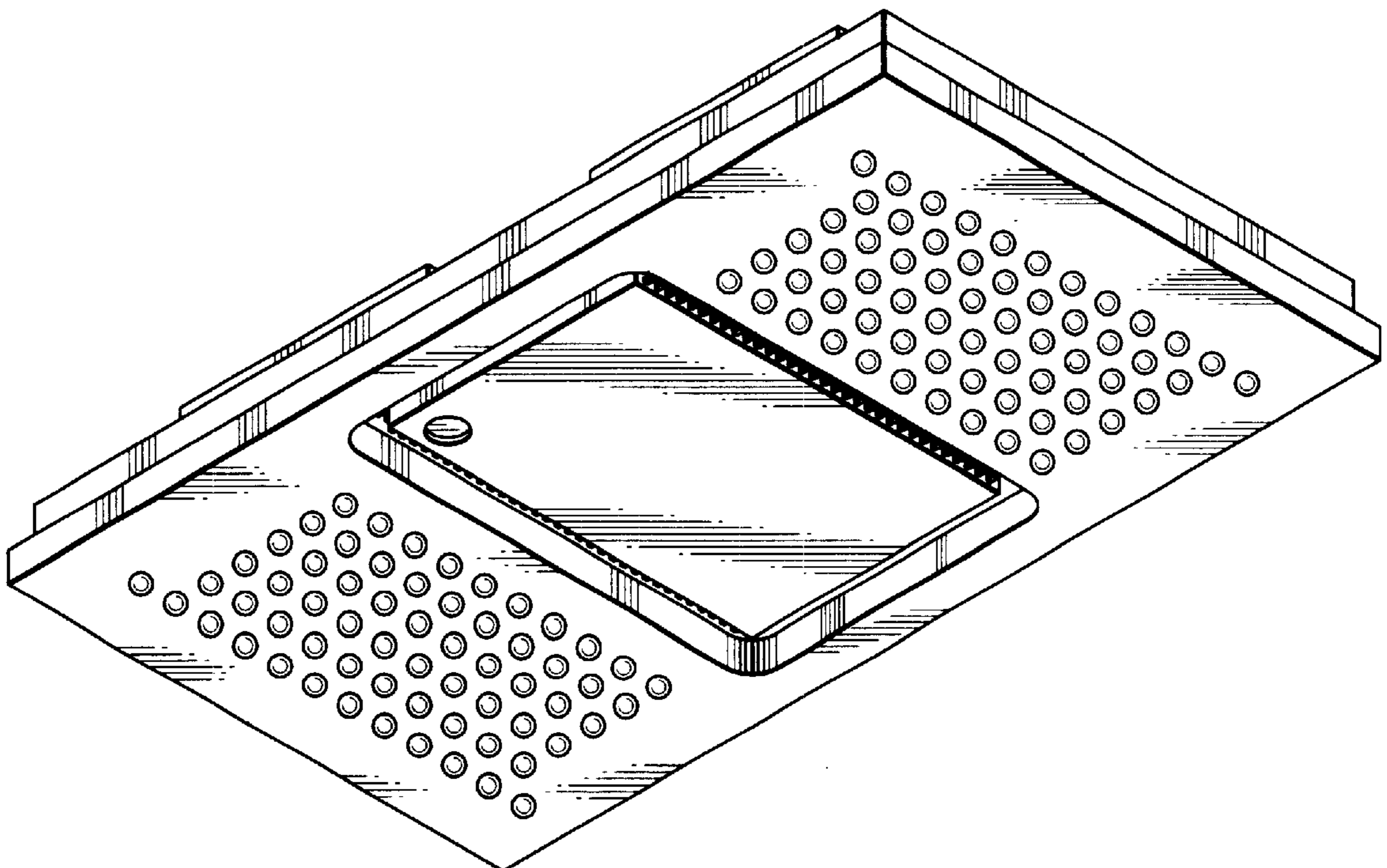


FIG.3

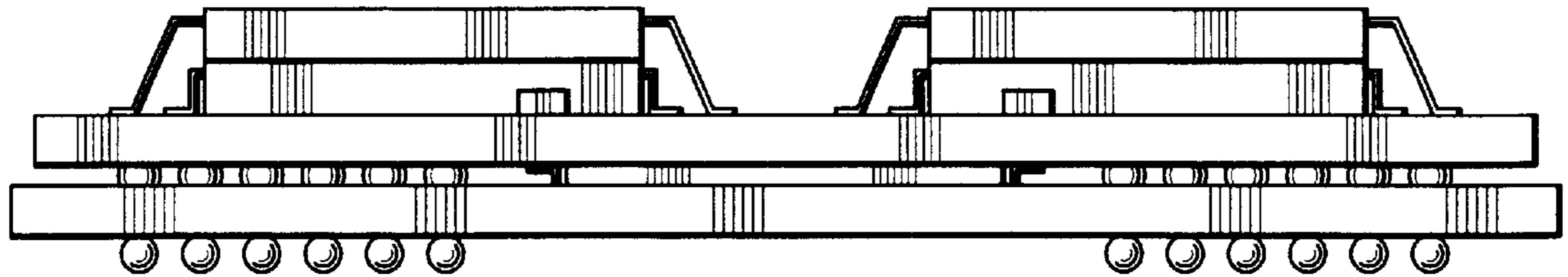


FIG.4

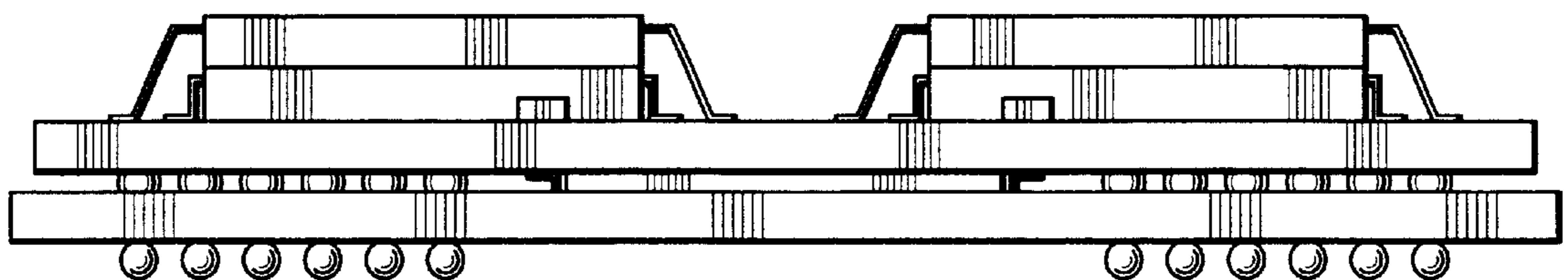


FIG.5

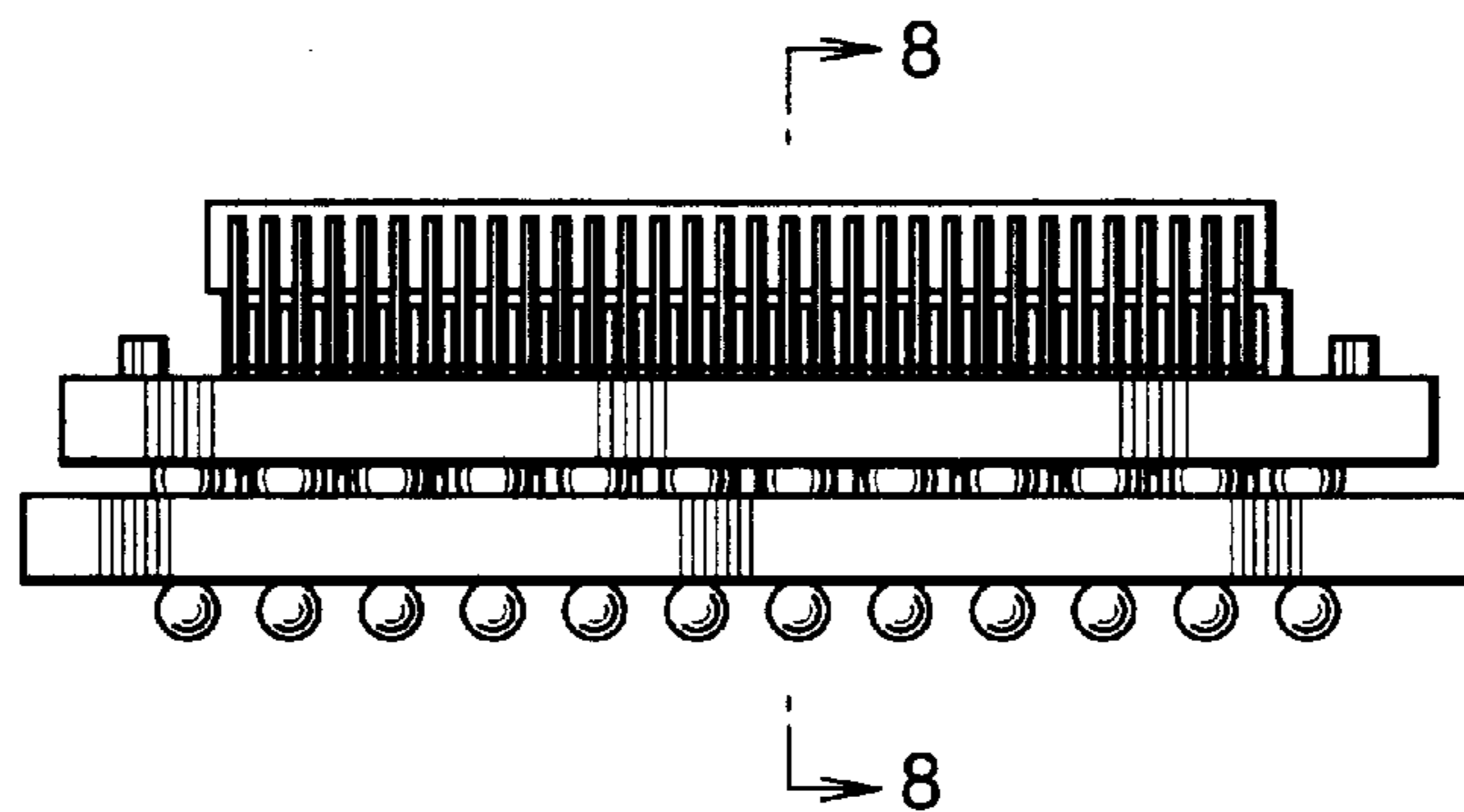


FIG. 6

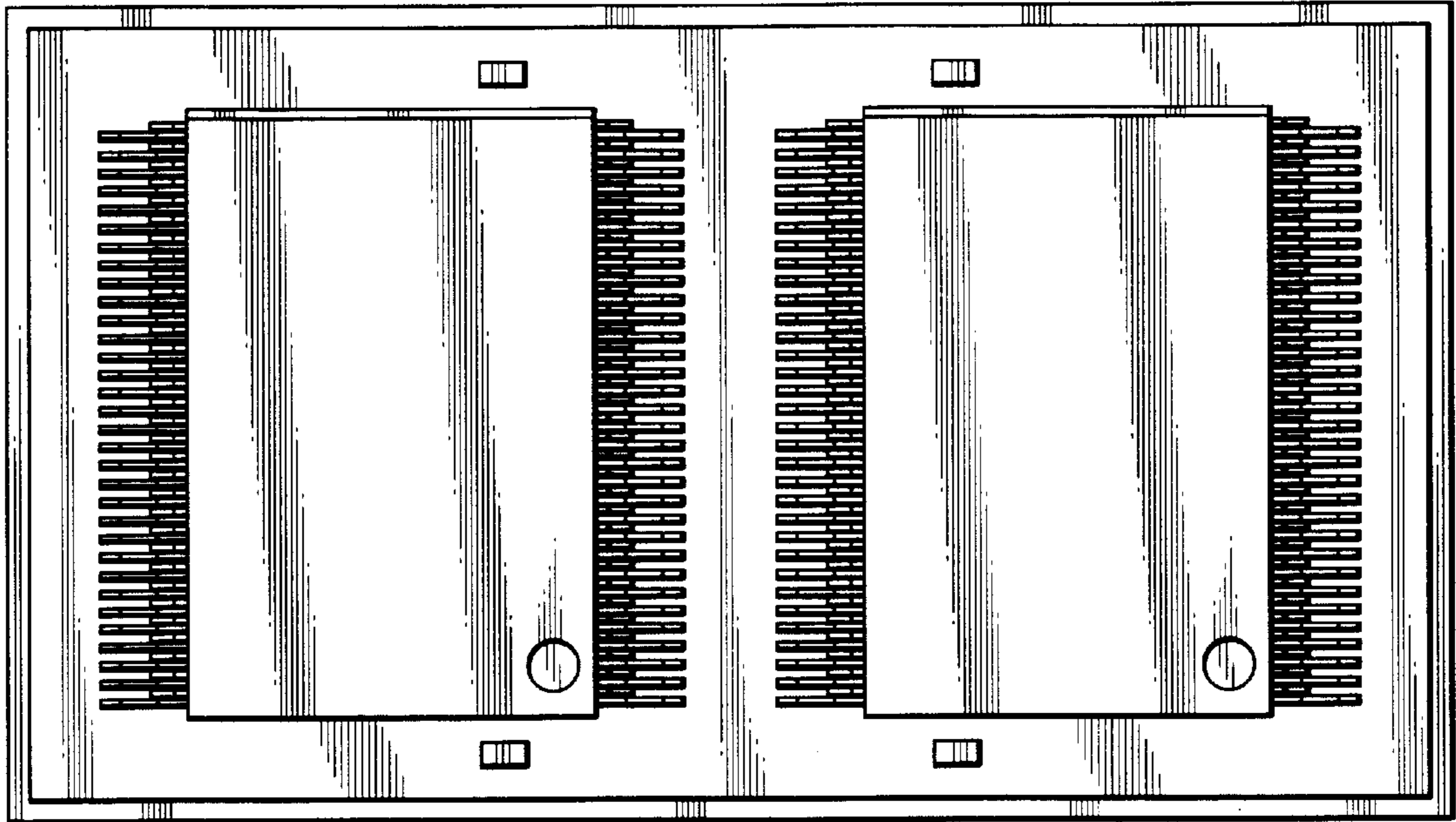


FIG. 7

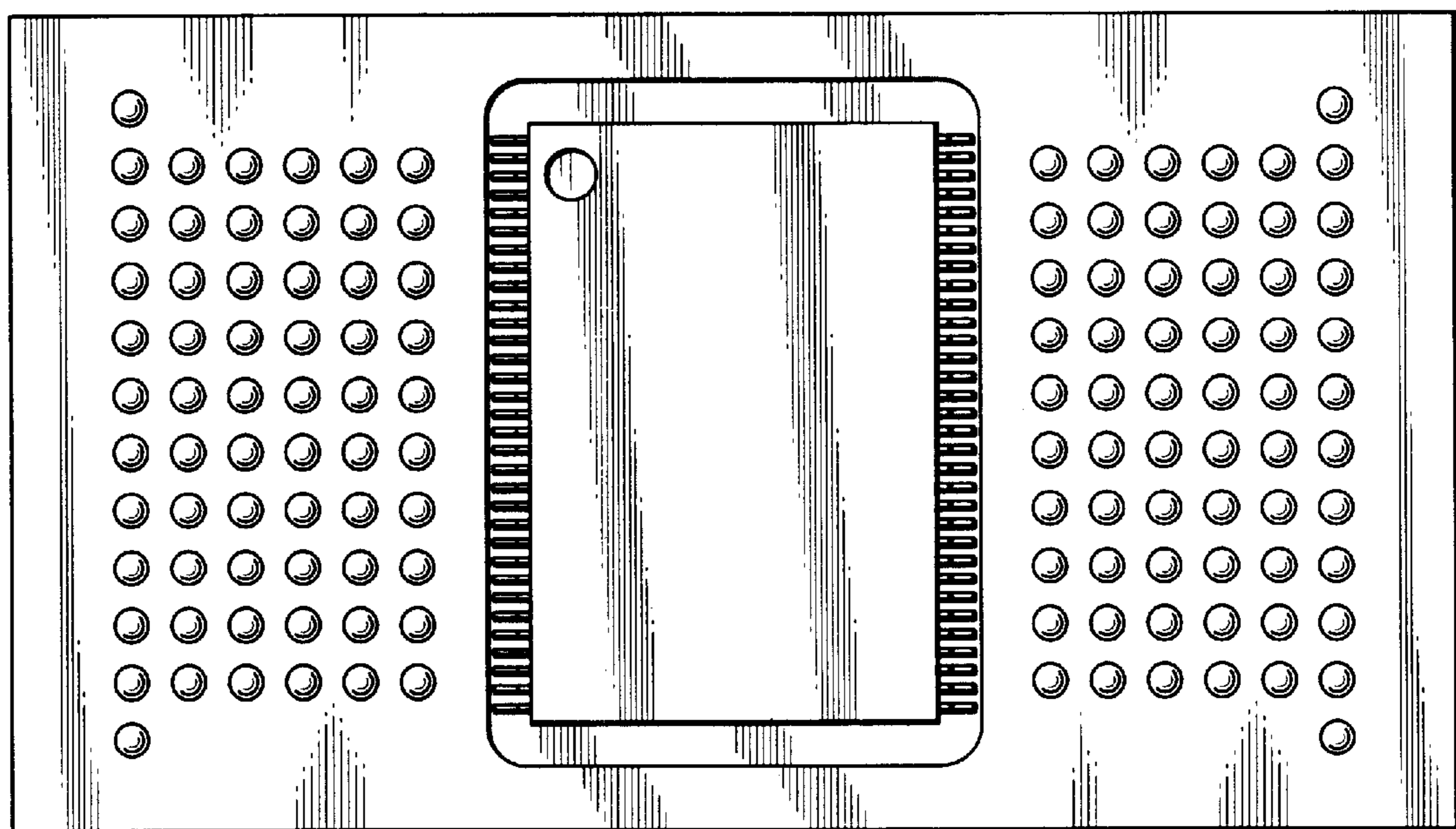


FIG. 8

